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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16ce625-04-ss

PIC16CE62X

4.2.2.2 OPTION REGISTER

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0 and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT (PSA = 1).

REGISTER 4-2: OPTION REGISTER (ADDRESS 81H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR reset
-x = Unknown at POR reset

bit 7: **RBPU**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6: **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5: **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

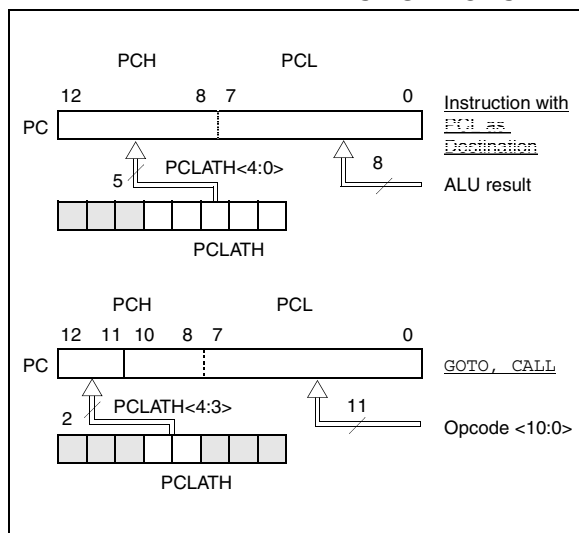
bit 2-0: **PS<2:0>**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

4.3 PCL and PCLATH

The program counter (PC) is 13 bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any reset, the PC is cleared. Figure 4-6 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 4-6: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note, "Implementing a Table Read" (AN556).

4.3.2 STACK

The PIC16CE62X family has an 8 level deep x 13-bit wide hardware stack (Figure 4-2 and Figure 4-3). The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no STATUS bits to indicate stack overflow or stack underflow conditions.

Note 2: There are no instruction/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions or the vectoring to an interrupt address.

FIGURE 5-3: BLOCK DIAGRAM OF RA3 PIN

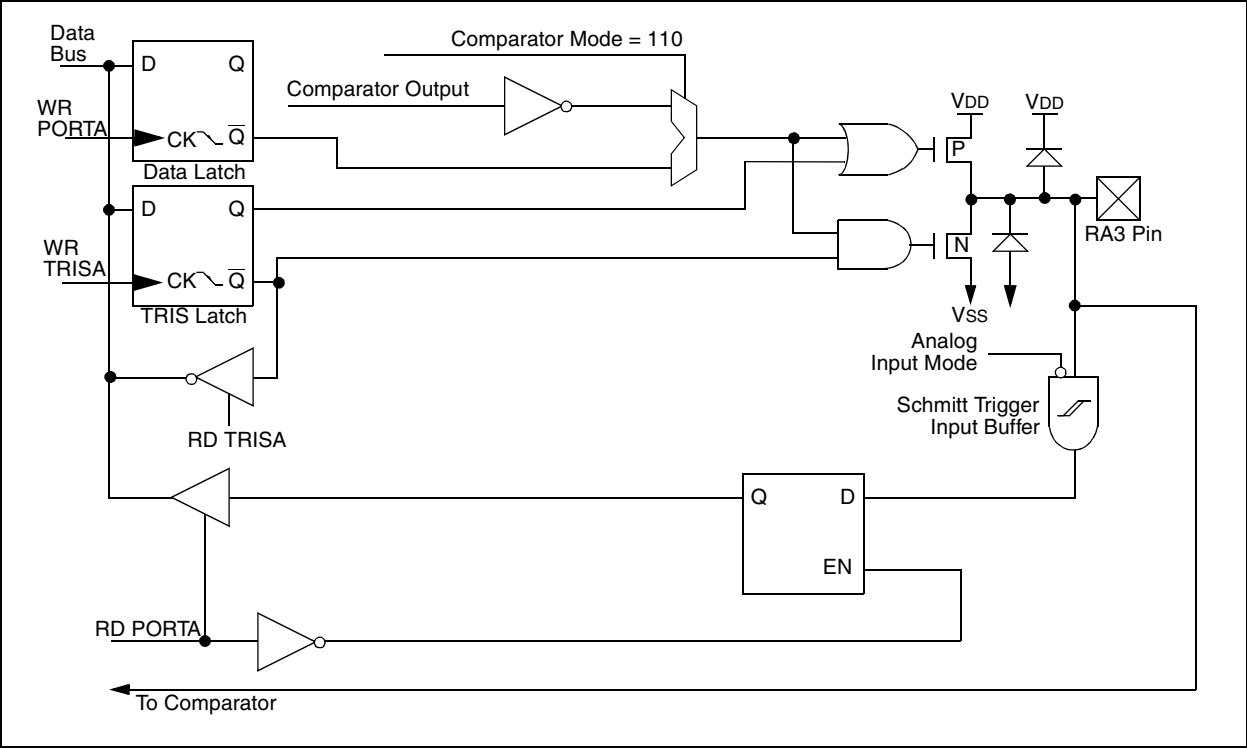
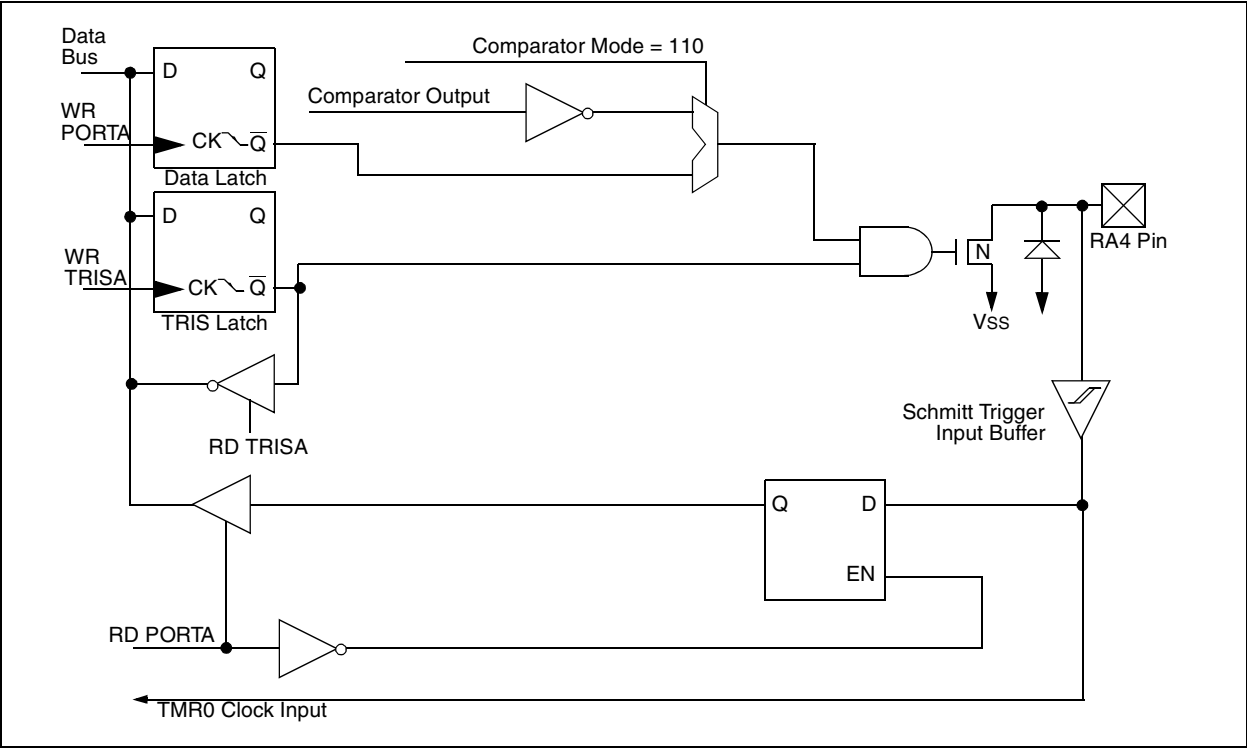


FIGURE 5-4: BLOCK DIAGRAM OF RA4 PIN



6.0 EEPROM PERIPHERAL OPERATION

The PIC16CE623/624/625 each have 128 bytes of EEPROM data memory. The EEPROM data memory supports a bi-directional, 2-wire bus and data transmission protocol. These two-wires are serial data (SDA) and serial clock (SCL), and are mapped to bit1 and bit2, respectively, of the EEINTF register (SFR 90h). In addition, the power to the EEPROM can be controlled using bit0 (EEVDD) of the EEINTF register. For most applications, all that is required is calls to the following functions:

```
; Byte_Write: Byte write routine
;   Inputs: EEPROM Address      EEADDR
;           EEPROM Data         EEDATA
;   Outputs: Return 01 in W if OK, else
;           return 00 in W
;
; Read_Current: Read EEPROM at address
;               currently held by EE device.
;   Inputs: NONE
;   Outputs: EEPROM Data         EEDATA
;           Return 01 in W if OK, else
;           return 00 in W
;
; Read_Random: Read EEPROM byte at supplied
; address
;   Inputs: EEPROM Address      EEADDR
;   Outputs: EEPROM Data         EEDATA
;           Return 01 in W if OK,
;           else return 00 in W
;
```

The code for these functions is available on our web site (www.microchip.com). The code will be accessed by either including the source code FL62XINC.ASM or by linking FLASH62X.ASM. FLASH62.IMC provides external definition to the calling program.

6.0.1 SERIAL DATA

SDA is a bi-directional pin used to transfer addresses and data into and data out of the memory.

For normal data transfer, SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the START and STOP conditions.

6.0.2 SERIAL CLOCK

This SCL input is used to synchronize the data transfer to and from the memory.

6.0.3 EEINTF REGISTER

The EEINTF register (SFR 90h) controls the access to the EEPROM. Register 6-1 details the function of each bit. User code must generate the clock and data signals.

REGISTER 6-1: EEINTF REGISTER (ADDRESS 90h)

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
—	—	—	—	—	EESCL	EESDA	EEVDD
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7-3: **Unimplemented:** Read as '0'

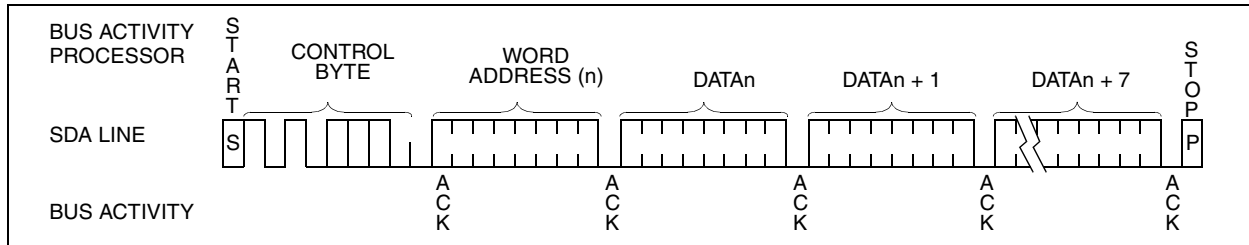
bit 2: **EESCL:** Clock line to the EEPROM
1 = Clock high
0 = Clock low

bit 1: **EESDA:** Data line to EEPROM
1 = Data line is high (pin is tri-stated, line is pulled high by a pull-up resistor)
0 = Data line is low

bit 0: **EEVDD:** VDD control bit for EEPROM
1 = VDD is turned on to EEPROM
0 = VDD is turned off to EEPROM (all pins are tri-stated and the EEPROM is powered down)

Note: EESDA, EESCL and EEVDD will read '0' if EEVDD is turned off.

FIGURE 6-6: PAGE WRITE



6.5 Read Operation

Read operations are initiated in the same way as write operations with the exception that the R/W bit of the EEPROM address is set to one. There are three basic types of read operations: current address read, random read, and sequential read.

6.6 Current Address Read

The EEPROM contains an address counter that maintains the address of the last word accessed, internally incremented by one. Therefore, if the previous access (either a read or write operation) was to address n , the next current address read operation would access data from address $n + 1$. Upon receipt of the EEPROM address with R/W bit set to one, the EEPROM issues an acknowledge and transmits the eight bit data word. The processor will not acknowledge the transfer, but does generate a stop condition and the EEPROM discontinues transmission (Figure 6-7).

6.7 Random Read

Random read operations allow the processor to access any memory location in a random manner. To perform this type of read operation, first the word address must be set. This is done by sending the word address to the EEPROM as part of a write operation. After the word address is sent, the processor generates a start condition following the acknowledge. This terminates the write operation, but not before the internal address pointer is set. Then the processor issues the control byte again, but with the R/W bit set to a one. The EEPROM will then issue an acknowledge and transmits the eight bit data word. The processor will not acknowledge the transfer, but does generate a stop condition and the EEPROM discontinues transmission (Figure 6-8).

6.8 Sequential Read

Sequential reads are initiated in the same way as a random read except that after the EEPROM transmits the first data byte, the processor issues an acknowledge as opposed to a stop condition in a random read. This directs the EEPROM to transmit the next sequentially addressed 8-bit word (Figure 6-9).

To provide sequential reads, the EEPROM contains an internal address pointer which is incremented by one at the completion of each operation. This address pointer allows the entire memory contents to be serially read during one operation.

6.9 Noise Protection

The EEPROM employs a V_{CC} threshold detector circuit, which disables the internal erase/write logic if the V_{CC} is below 1.5 volts at nominal conditions.

The SCL and SDA inputs have Schmitt trigger and filter circuits, which suppress noise spikes to assure proper device operation even on a noisy bus.

FIGURE 7-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2

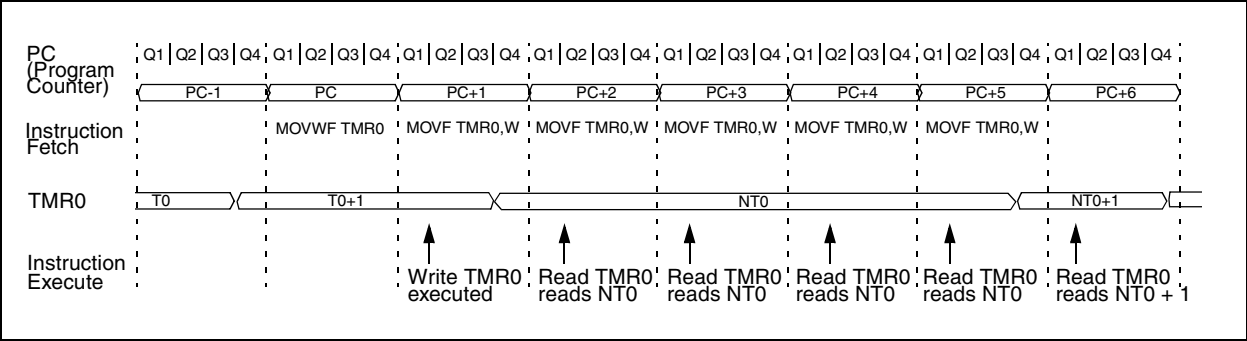
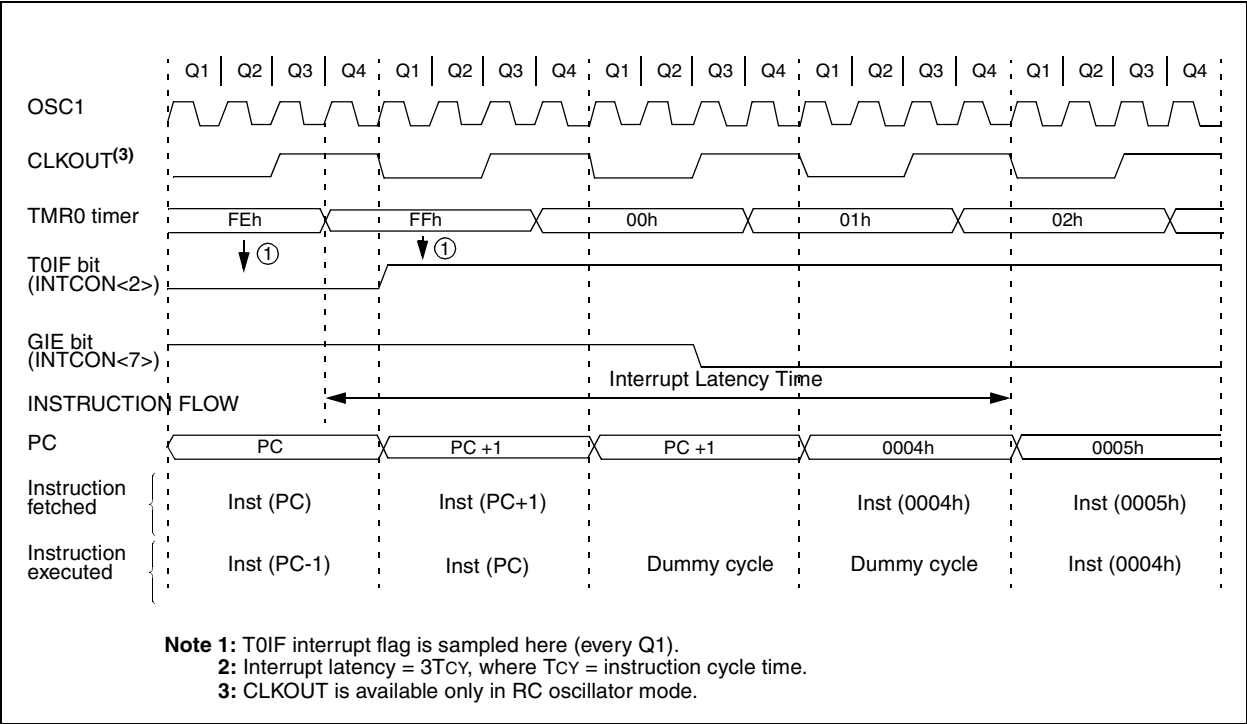


FIGURE 7-4: TIMER0 INTERRUPT TIMING



PIC16CE62X

NOTES:

8.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with the RA0 through RA3 pins. The on-chip voltage reference (Section 9.0) can also be an input to the comparators.

The CMCON register, shown in Register 8-1, controls the comparator input and output multiplexers. A block diagram of the comparator is shown in Figure 8-1.

REGISTER 8-1: CMCON REGISTER (ADDRESS 1Fh)

R-0	R-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0
bit7				bit0			

R = Readable bit
W = Writable bit
U = Unimplemented bit,
read as '0'
- n = Value at POR reset

bit 7: **C2OUT**: Comparator 2 output
1 = C2 VIN+ > C2 VIN–
0 = C2 VIN+ < C2 VIN–

bit 6: **C1OUT**: Comparator 1 output
1 = C1 VIN+ > C1 VIN–
0 = C1 VIN+ < C1 VIN–

bit 5-4: **Unimplemented**: Read as '0'

bit 3: **CIS**: Comparator Input Switch
When CM<2:0> = 001:
1 = C1 VIN– connects to RA3
0 = C1 VIN– connects to RA0
When CM<2:0> = 010:
1 = C1 VIN– connects to RA3
C2 VIN– connects to RA2
0 = C1 VIN– connects to RA0
C2 VIN– connects to RA1

bit 2-0: **CM<2:0>**: Comparator mode
Figure 8-1.

FIGURE 10-11: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW V_{DD} POWER-UP)

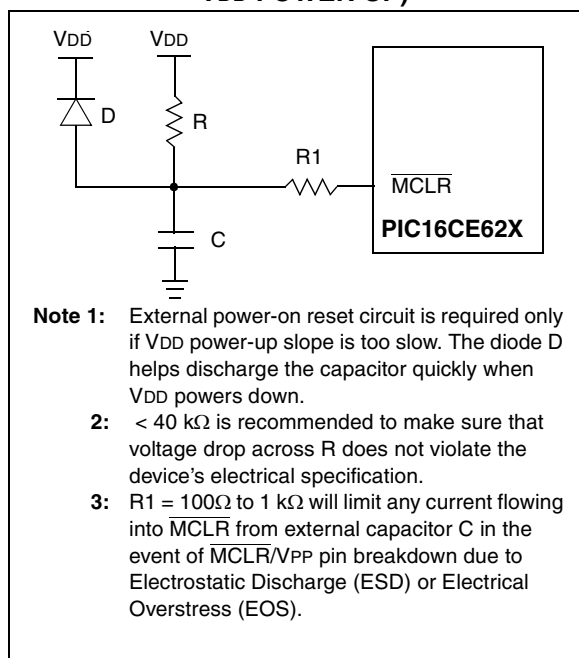


FIGURE 10-12: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1

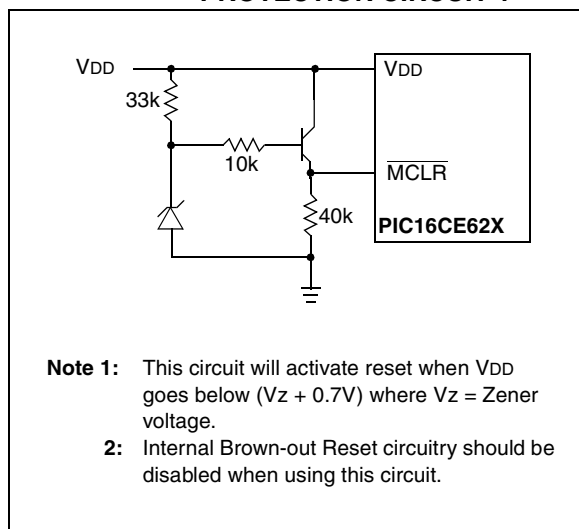


FIGURE 10-13: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2

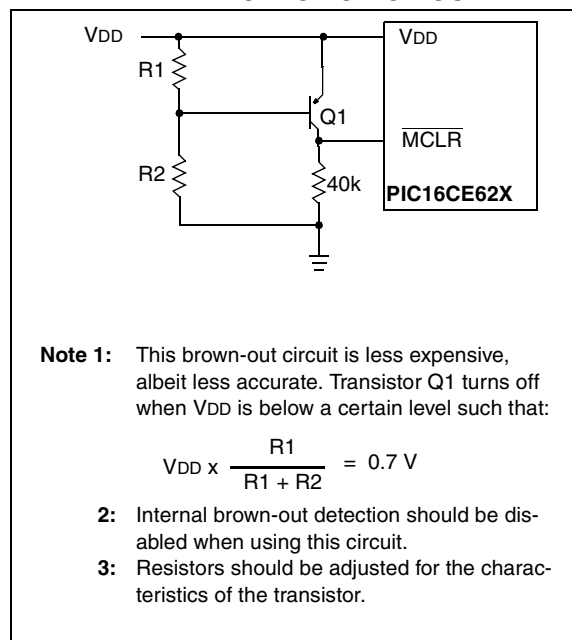


FIGURE 10-14: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3

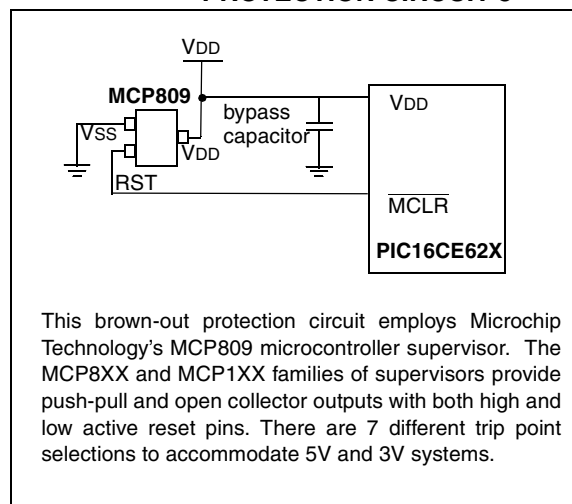


FIGURE 10-17: WATCHDOG TIMER BLOCK DIAGRAM

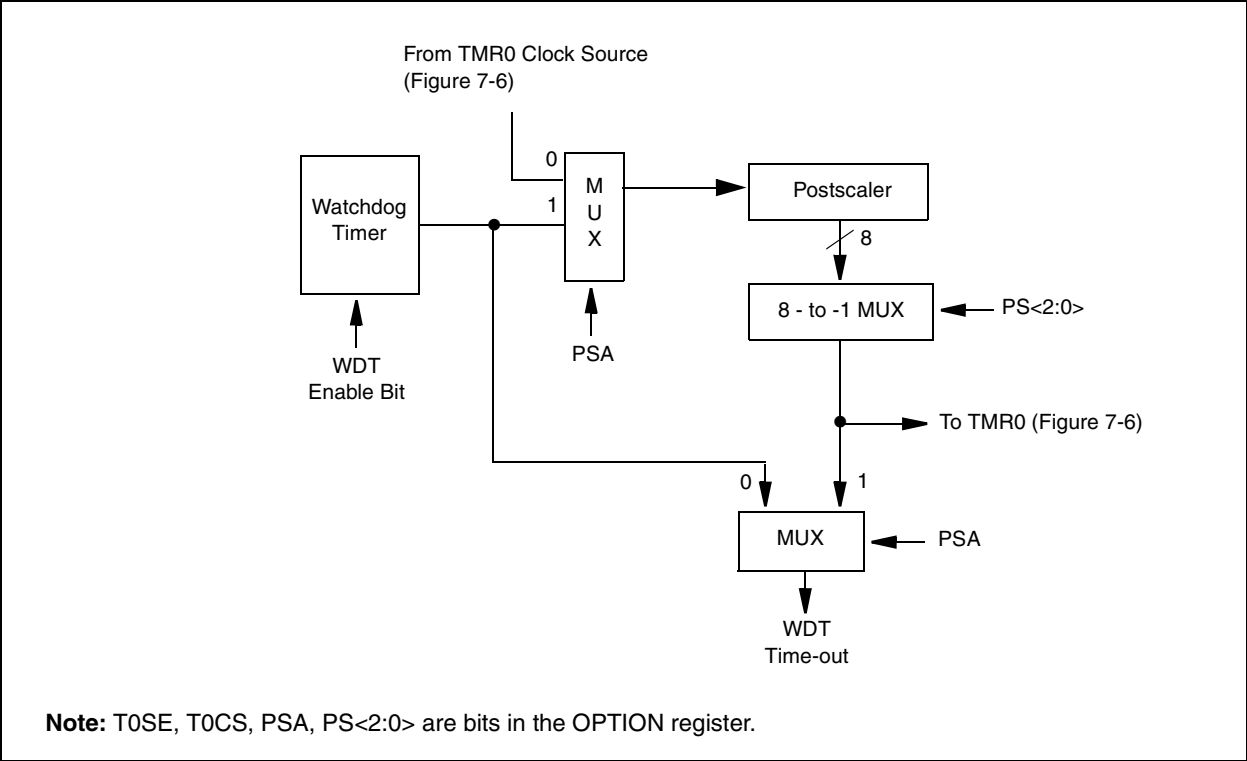


FIGURE 10-18: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	—	BOREN	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0
81h	OPTION	RBP $\overline{U}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0

Legend: – = Unimplemented location, read as “0”, + = Reserved for future use

Note: Shaded cells are not used by the Watchdog Timer.

10.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{PD}$ bit in the STATUS register is cleared, the $\overline{TO}$ bit is set and the oscillator driver is turned off. The I/O ports maintain the status they had before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD or VSS, with no external circuitry drawing current from the I/O pin, and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level (V_{IHMC}).

Note: It should be noted that a RESET generated by a WDT time-out does not drive $\overline{MCLR}$ pin low.

The first event will cause a device reset. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device reset. $\overline{PD}$ bit, which is set on power-up is cleared when SLEEP is invoked. $\overline{TO}$ bit is cleared if WDT wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note: If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from sleep. The sleep instruction is completely executed.

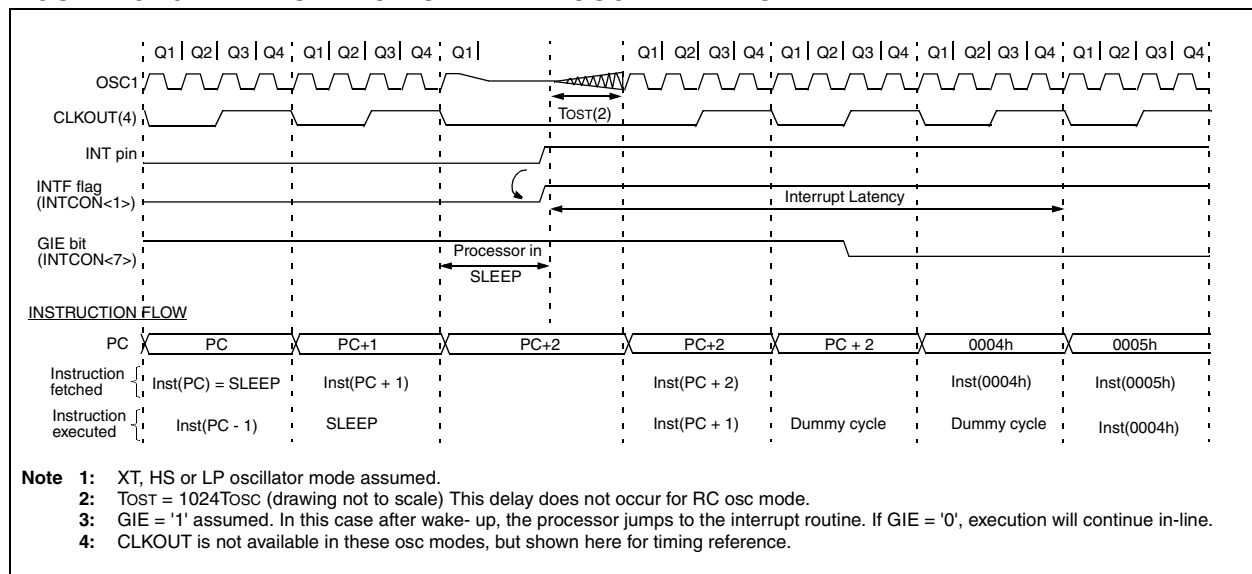
10.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External reset input on $\overline{MCLR}$ pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

The WDT is cleared when the device wakes-up from sleep, regardless of the source of wake-up.

FIGURE 10-19: WAKE-UP FROM SLEEP THROUGH INTERRUPT



PIC16CE62X

13.1 DC CHARACTERISTICS:

PIC16CE62X-04 (Commercial, Industrial, Extended)

PIC16CE62X-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature				
			-40°C ≤ TA ≤ +85°C for industrial and				
			0°C ≤ TA ≤ +70°C for commercial and				
			-40°C ≤ TA ≤ +125°C for extended				
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2, 4)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)*
			—	0.4	1.2	mA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT osc mode, (Note 4)
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS osc mode, (Note 6)
			—	4.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS osc mode
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS osc mode
			—	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	—	—	2.2	μA	VDD = 3.0V
			—	—	5.0	μA	VDD = 4.5V*
			—	—	9.0	μA	VDD = 5.5V
			—	—	15	μA	VDD = 5.5V Extended
D022	ΔI _{WDT}	WDT Current (Note 5)	—	6.0	10	μA	VDD = 4.0V (125°C)
D022A	ΔI _{BOR}	Brown-out Reset Current (Note 5)	—	75	125	μA	BOD enabled, VDD = 5.0V
D023	ΔI _{COMP}	Comparator Current for each Comparator (Note 5)	—	30	60	μA	VDD = 4.0V
D023A	ΔI _{VREF}	VREF Current (Note 5)	—	80	135	μA	VDD = 4.0V
	ΔI _{EE Write}	Operating Current	—	—	3	mA	VCC = 5.5V, SCL = 400 kHz
	ΔI _{EE Read}	Operating Current	—	—	1	mA	
	ΔI _{EE}	Standby Current	—	—	30	μA	VCC = 3.0V, EE VDD = VCC
	ΔI _{EE}	Standby Current	—	—	100	μA	VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula $I_r = VDD/2R_{ext}$ (mA) with Rext in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

13.2 DC CHARACTERISTICS: PIC16LCE62X-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature				
			$-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	.05*	—	—	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)*
			—	—	1.1	mA	FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT osc mode, (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	—	—	2.0	μA	VDD = 2.5V
			—	—	2.2	μA	VDD = 3.0V*
			—	—	9.0	μA	VDD = 5.5V
			—	—	15	μA	VDD = 5.5V Extended
D022	ΔIWD	WDT Current (Note 5)	—	6.0	10	μA	VDD=4.0V
D022A	ΔIBOR	Brown-out Reset Current (Note 5)	—	75	125	μA	(125°C) BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator (Note 5)	—	30	60	μA	VDD = 4.0V
D023A	ΔIVREF	VREF Current (Note 5)	—	80	135	μA	VDD = 4.0V
	ΔIEE Write	Operating Current	—	—	3	mA	VCC = 5.5V, SCL = 400 kHz
	ΔIEE Read	Operating Current	—	—	1	mA	
	ΔIEE	Standby Current	—	—	30	μA	VCC = 3.0V, EE VDD = VCC
	ΔIEE	Standby Current	—	—	100	μA	VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula $I_r = V_{DD}/2R_{ext}$ (mA) with Rext in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

PIC16CE62X

13.4 Timing Parameter Symbology

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

T			
F	Frequency	T	Time
Lowercase subscripts (pp) and their meanings:			
pp			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	MCLR		
Uppercase letters and their meanings:			
S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 13-4: LOAD CONDITIONS

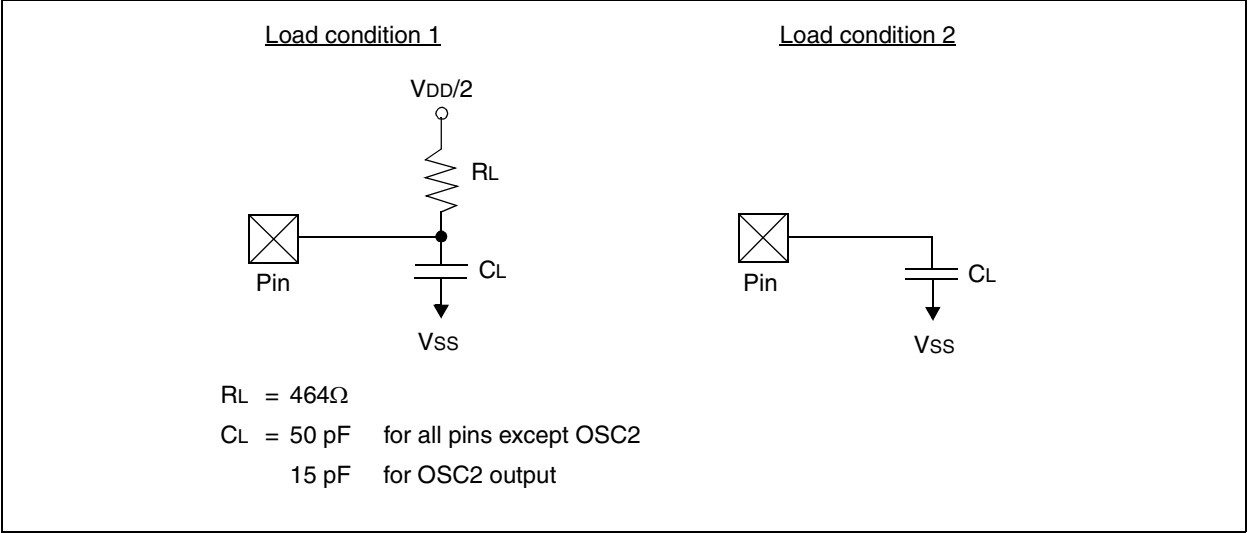


FIGURE 13-7: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

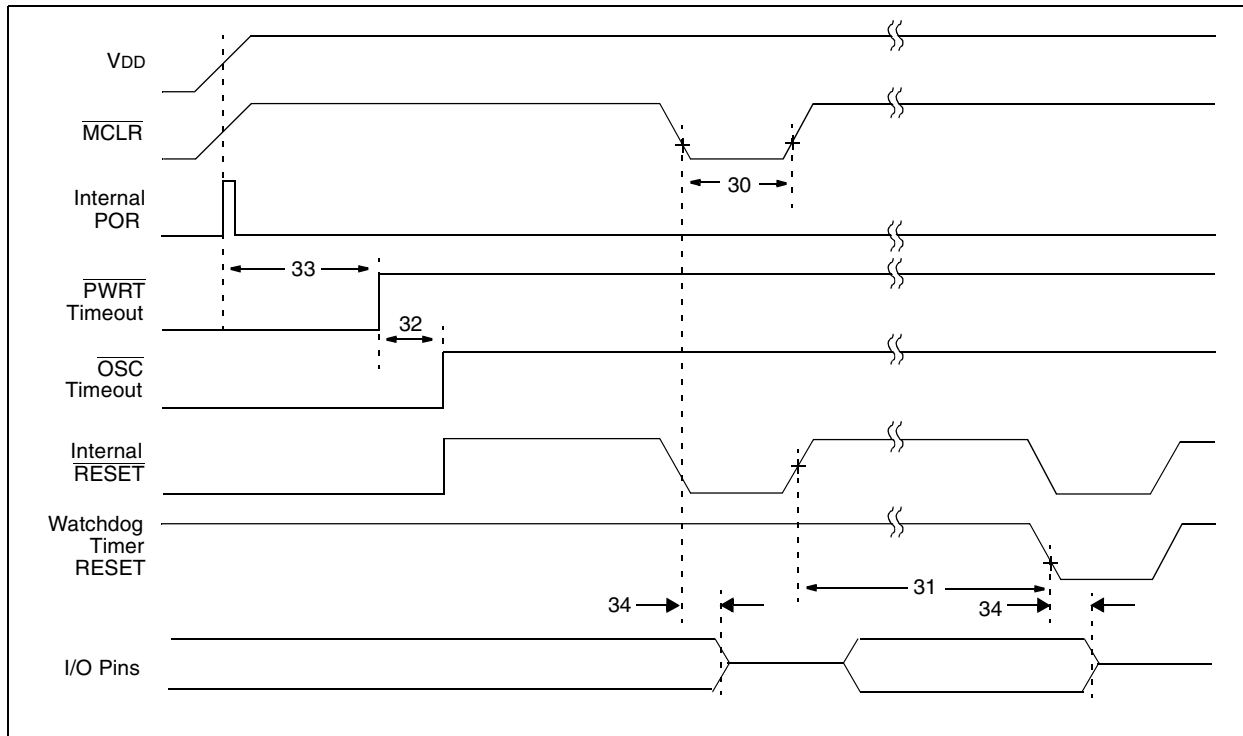


FIGURE 13-8: BROWN-OUT RESET TIMING

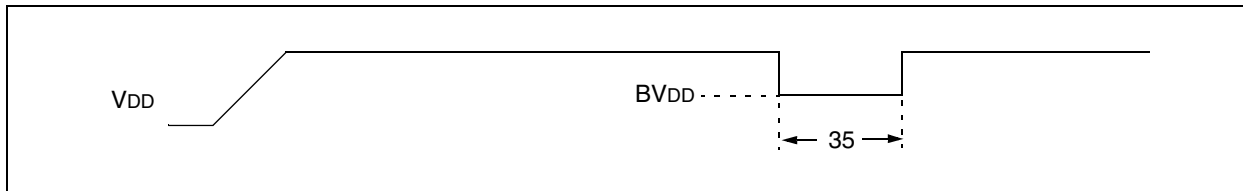


TABLE 13-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

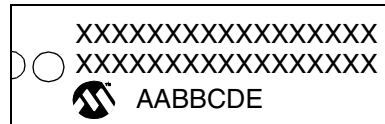
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	Tmcl	MCLR Pulse Width (low)	2000	—	—	ns	-40° to +85°C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	VDD = 5.0V, -40° to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	VDD = 5.0V, -40° to +85°C
34	Tioz	I/O hi-impedance from MCLR low	—	—	2.0	μs	
35	TBOR	Brown-out Reset Pulse Width	100*	—	—	μs	3.7V ≤ VDD ≤ 4.3V

* These parameters are characterized but not tested.

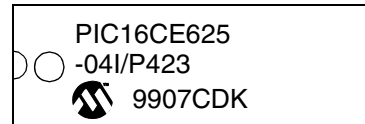
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

14.1 Package Marking Information

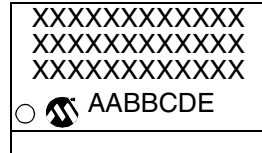
18-Lead PDIP



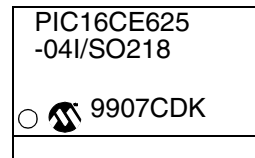
Example



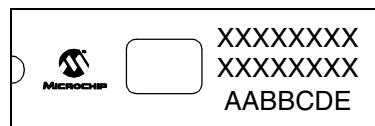
18-Lead SOIC (.300")



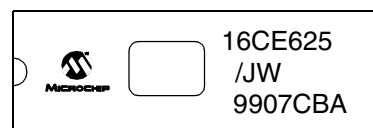
Example



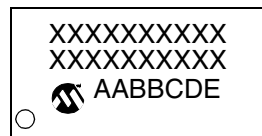
18-Lead CERDIP Windowed



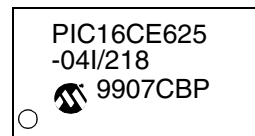
Example



20-Lead SSOP



Example



Legend:

XX...X	Customer-specific information
Y	Year code (last digit of calendar year)
YY	Year code (last 2 digits of calendar year)
WW	Week code (week of January 1 is week '01')
NNN	Alphanumeric traceability code
(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

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NOTES:

PIC16XXXXXX FAMILY

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